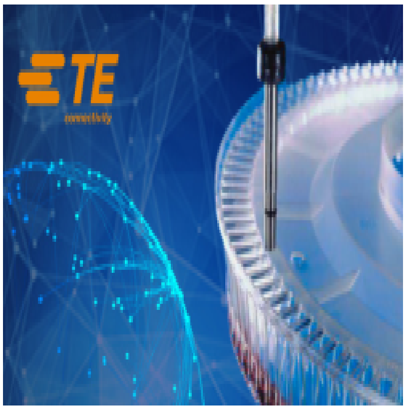

Precision Non-Contact Level & Distance Measurement, Ready to Ship from CDI

Description

When your process depends on fast, repeatable measurements using non-touch sensing, the ML Series ultrasonic micromeasurement platform from TE Connectivity is a smart fit. Component Distributors Inc. (CDI) is highlighting two key items that help you deploy the system quickly: the 11011239-00 ML-01 Electronics Module and the CBL-Q1A0S2-10 quick-disconnect cable.

ML-01 Electronics Module (Single channel, two relays)

The 11011239-00 is the ML-01 electronics module used with ML Series ultrasonic sensors, providing 24 VDC input power, a NEMA 1 enclosure, RS-232 communication, and two relays for control/alarms in automation environments. It is one of the three required ML Series building blocks (sensor, cable, electronics unit), and CDI notes it is available to ship.

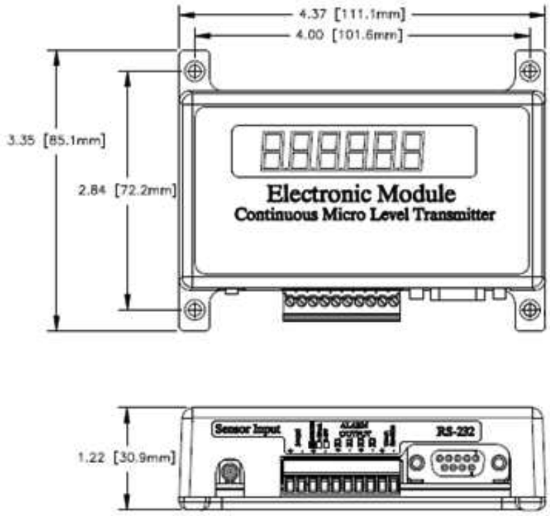

Figure 1: ML series elements electronic module

CBL-Q1A0S2-10: Quick-disconnect cable (10 ft) for fast installation

The CBL-Q1A0S2-10 is a 10-foot quick-disconnect cable that connects the ML Series sensor to the electronics module, using RG174 to an SMB connection for use with the 098-10001 ultrasonic sensor and the 11011239-00 module. CDI also notes this cable is in stock and can ship.

Why ML Series for these applications

The ML Series is designed for high-speed, multipoint, non-contact ultrasonic measurement, delivering Â±0.0075 in (Â±0.19 mm) accuracy with performance that is not affected by liquid color and does not disturb the sample because nothing touches the media. Many operational settings can be programmed through a serial port for application-specific customization.

Applications

CDI can target customers using ultrasonic measurement for any of the following applications: adhesive application, auto sampler, bottle filling, dimensional profiling, drum/tote level, fill verification, machine run-out, material thickness, robotic arm position, shapes/profiling, valve/tool position, wafer counting, and wafer profiling.

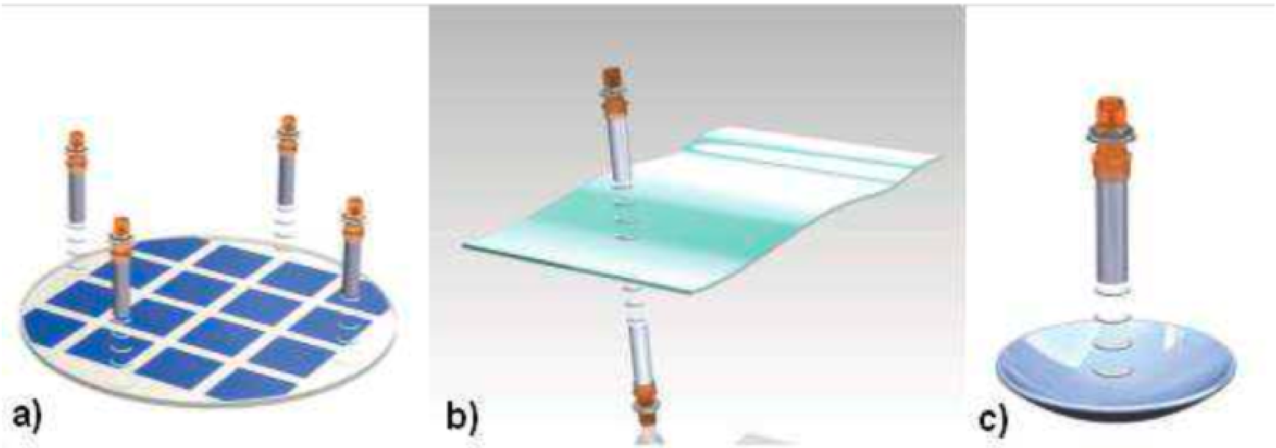

Figure 3: Applications of ML series elements; a) Semiconductor wafer profile, evenness, flatness, bow, warpage; b) Thic measurement; c) Optics and contacts and lens thickness and curvature on-line inspection

Get started now

Use CDIâ€™s product pages for **11011239-00** and **CBL-Q1A0S2-10** to request a quote or technical support and confirm shipping for your build schedule.

Category

1. Automation & Controls
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